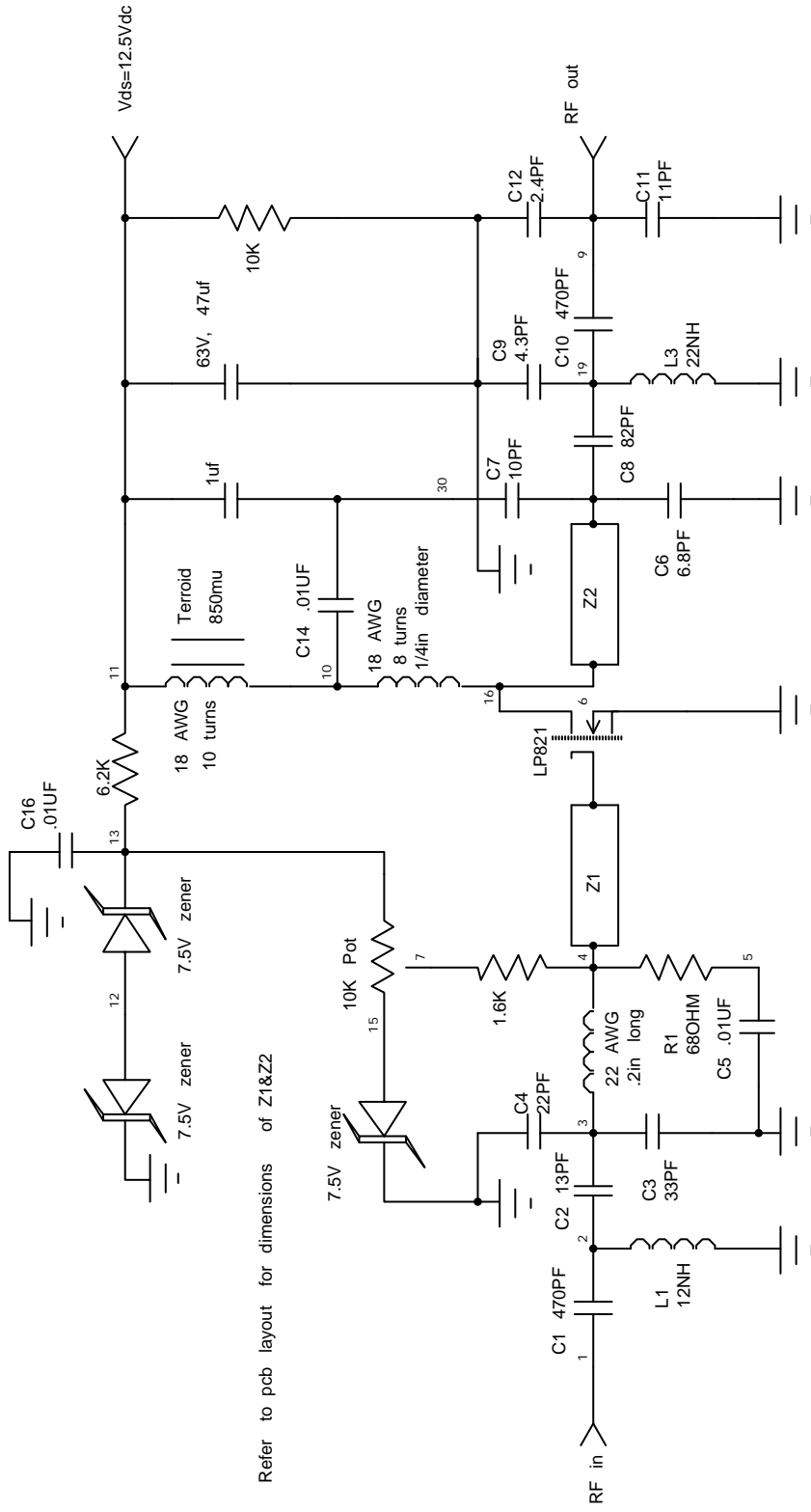


PCB Material Double Side FR4
 ER=4.5 H=32 T=1.4

POLYFET TEST FIXTURE
 450--470MHZ

SYMBOL	VALUE	DESCRIPTION
C01, C10	470pf	ATC-100B Chip Cap.
C02	13pf	ATC-100B Chip Cap.
C03, C04	22k-33pf	ATC-100B Chip Cap.
C05, C11, C12	0.01uF	ATC-100B Chip Cap.
C06	NA	ATC-100B Chip Cap.
C07, C08	100k, 2pf	ATC-100B Chip Cap.
C09	82pf	ATC-100B Chip Cap.
C13	0.01uF	Tantalum Cap.
C14	47uF	63V Electrolytic Cap.
C15&16	2.4k, 110f	ATC-100B Chip Cap.
L01	12mH	1210 Chip Ind.
L02	1	Straight wire.
L03*	1	Weld M/N
L04	22nh	#18AWG / 0.55inch / 3 Turns
L05	---	#18AWG / 0.55inch / 8 Turns
L06	---	Ferr. #18AWG 10 Turns
R01	58ohm	1206 Chip Res.
R02	1.6k	1206 Chip Res.
R03	62k	1206 Chip Res.
P01	10k	6x6mm Potentiometer
Z01	7.5V	50mA Zener Diode
D01, D02	7.5V	50mA Chip Diode
VDD	12.5V	DC Power Supply
Bias	400mA	Bias Current

DRN BY: ZHOU JUN	BR/00/00	POLYFET RF DEVICES	
CHKD :		TB147, 450-470MHZ	
ELECT :		SIZE (FSON N0)	REV
MECH :		LP821, 10W FM	1
PRDC :		SCALE : 1 : 1	SHEET 1 OF 2
QVAL :			
PGMS :			



Refer to pcb layout for dimensions of Z1&Z2

DRN :	J Citrolo	10/26/00
CHK :	E. Greenbaum	10/26/00
ELECT :		
MECH :	K. S. Tay	10/26/00
PROC :		
QUAL :		
PGMS :		

Polyfet RF Devices		
450-470MHz, 10W, 12.5V		
Size	FSCM NO	Rev
TB 147		
Scale	Sheet 1 of 1	